

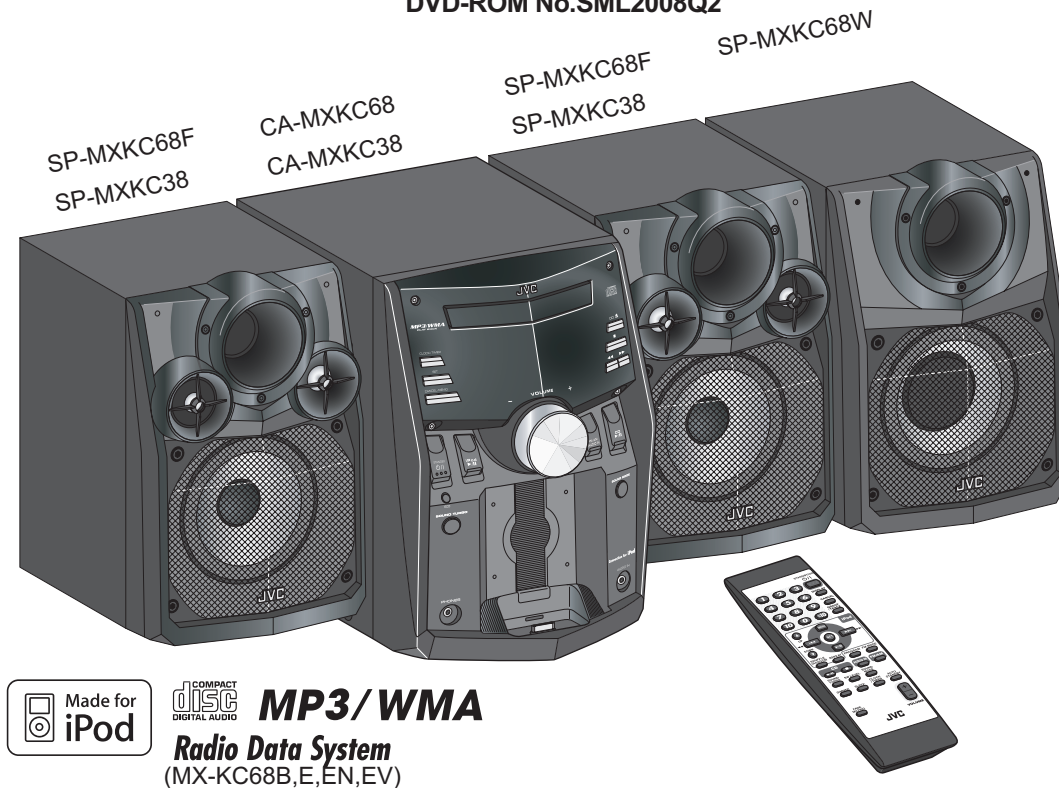
# JVC

## SCHEMATIC DIAGRAMS

### COMPACT COMPONENT SYSTEM

**MX-KC68J, MX-KC68C, MX-KC68B,  
MX-KC68E, MX-KC68EN, MX-KC68EV,  
MX-KC68A, MX-KC68UJ, MX-KC68UW,  
MX-KC38J, MX-KC38C**

DVD-ROM No.SML2008Q2



**MP3/WMA**

**Radio Data System**  
(MX-KC68B,E,EN,EV)

Lead free solder used in the board (material : Sn-Ag-Cu, melting point : 219 Centigrade)

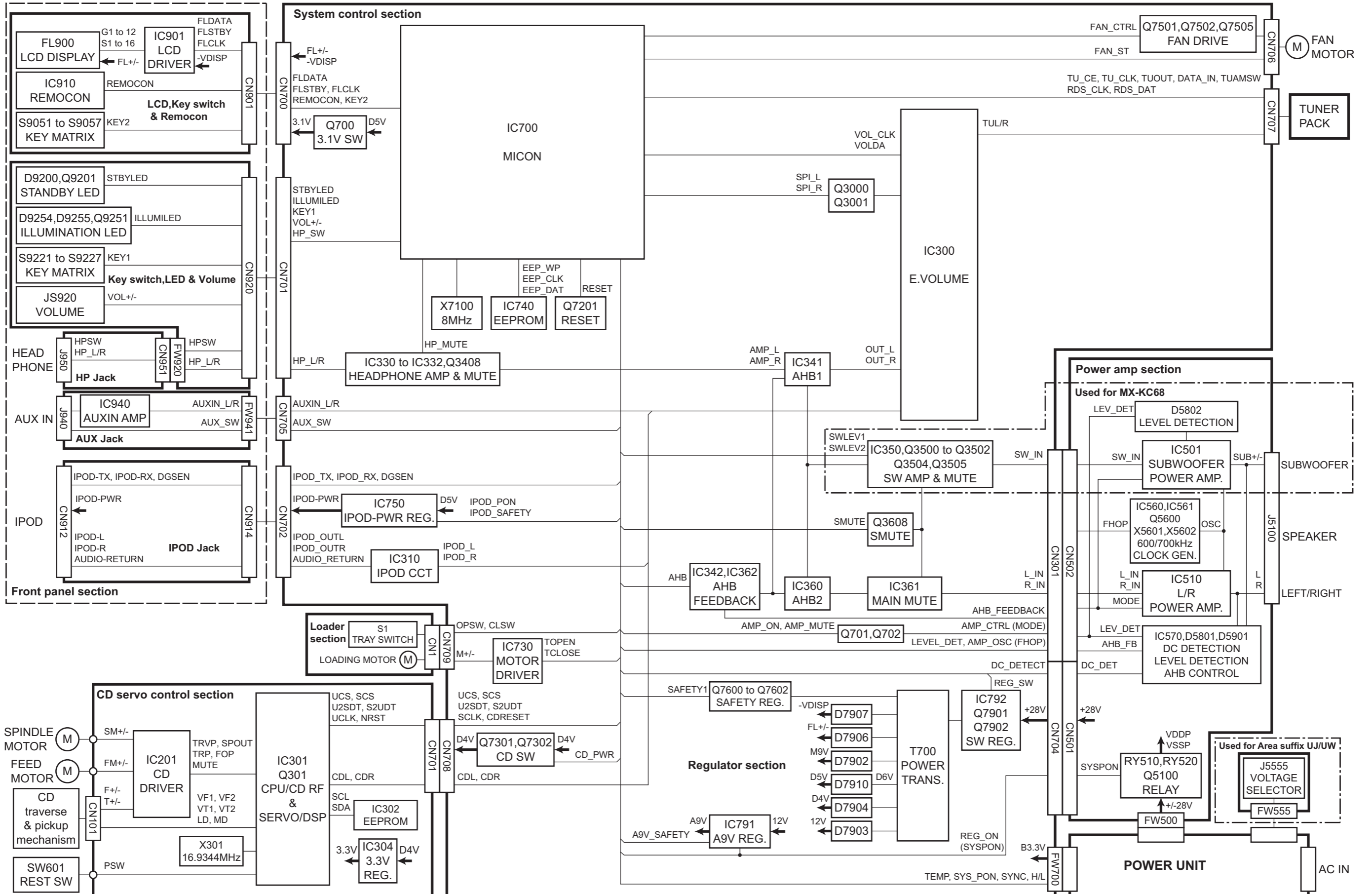
Lead free solder used in the board (material : Sn-Cu, melting point : 230 Centigrade)

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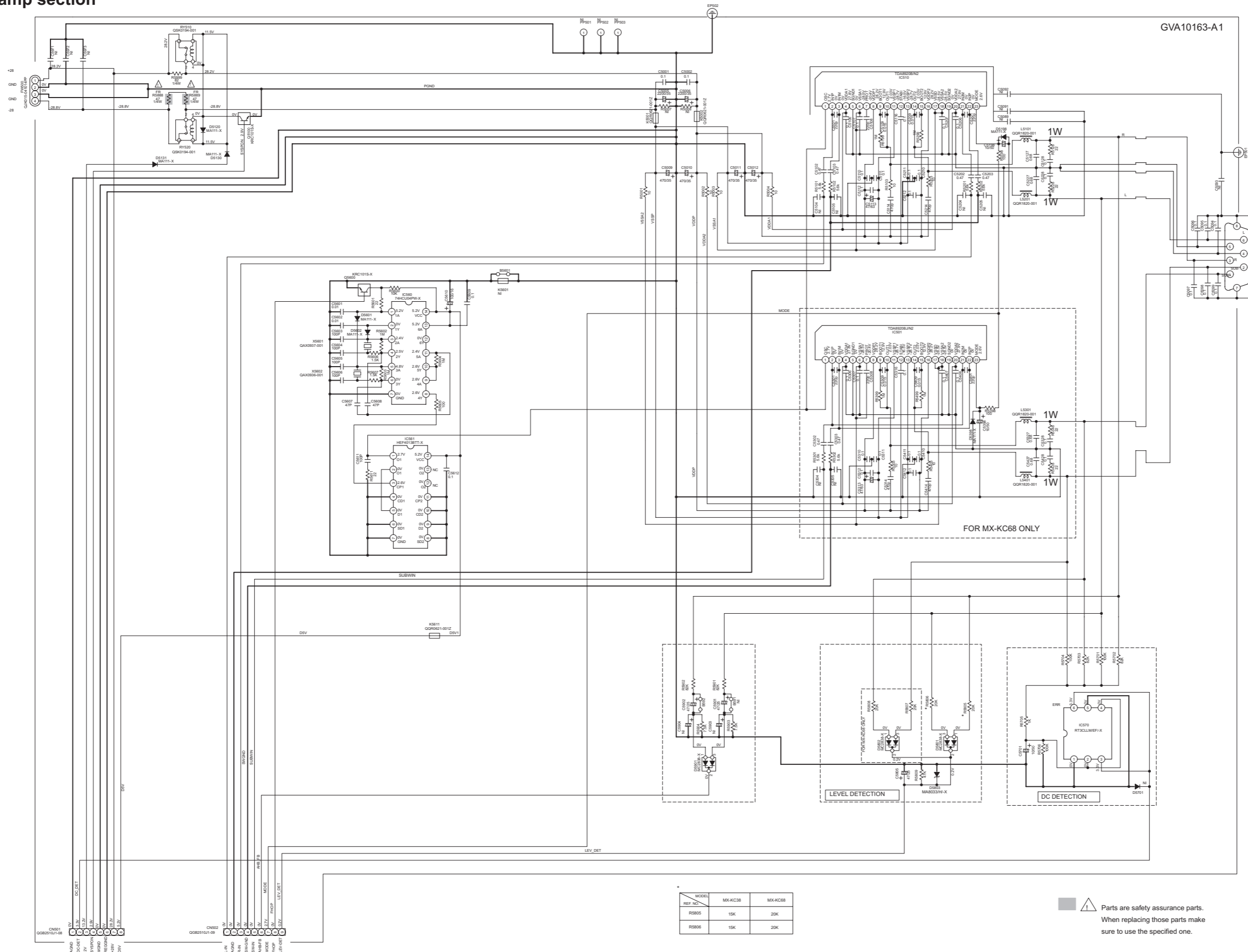
In regard with component parts appearing on the silk-screen printed side (parts side) of the PWB diagrams, the parts that are printed over with black such as the resistor (■), diode (▣) and ICP (●) or identified by the "▲" mark nearby are critical for safety.

# Block diagram



# Standard schematic diagrams

## ■ Pre-amp section

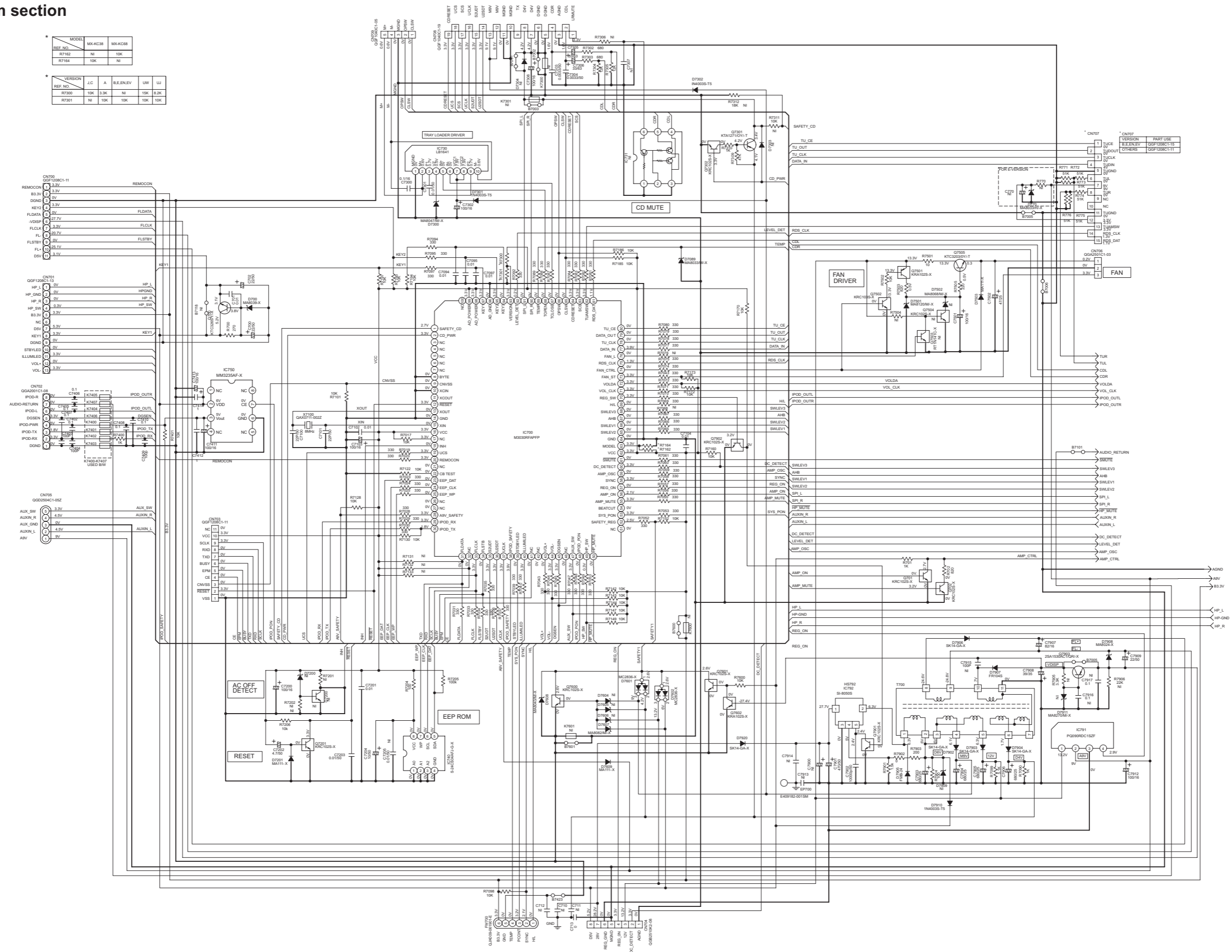


Parts are safety assurance parts.  
When replacing those parts make  
sure to use the specified one.

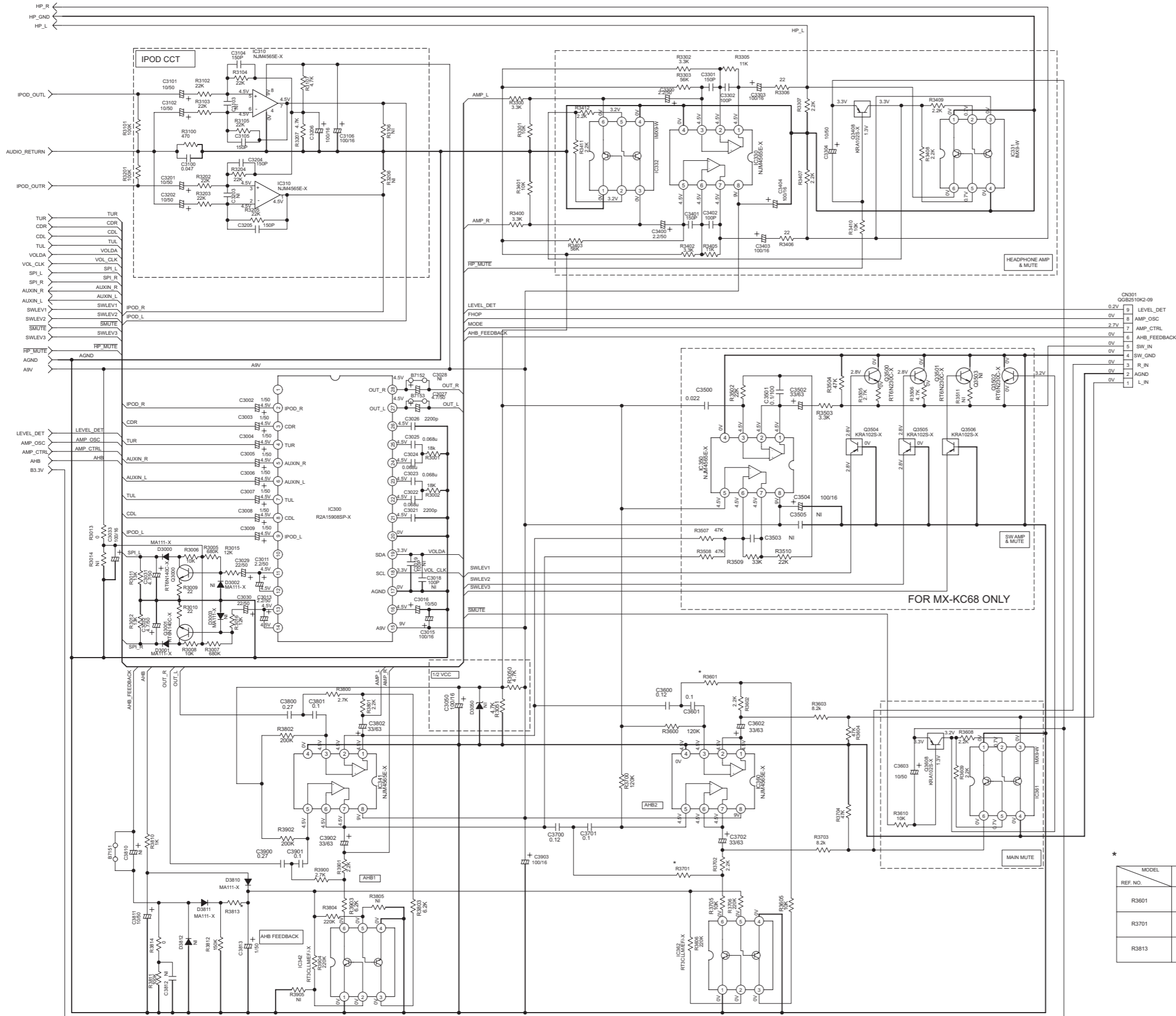
■ Micom section

REF. NO.	MODEL	MX-KC3R	MX-KC3B
R7162	NI	10K	
R7164	NI	10K	

VERSION	J.C.	A	B.E.LEV	UW	UJ
R7300	10K	3.3K	NI	10K	8.2K
R7301	NI	10K	10K	10K	10K



■ Amp section



CN301  
QGB2510K2-09

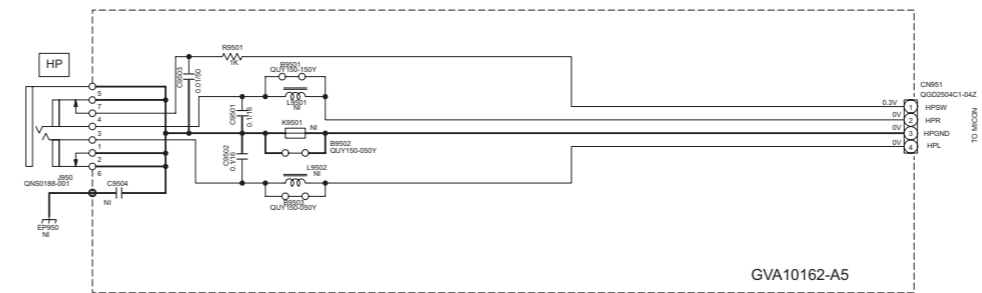
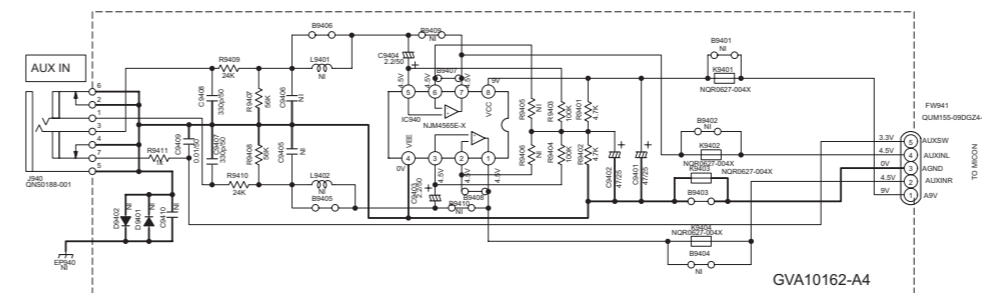
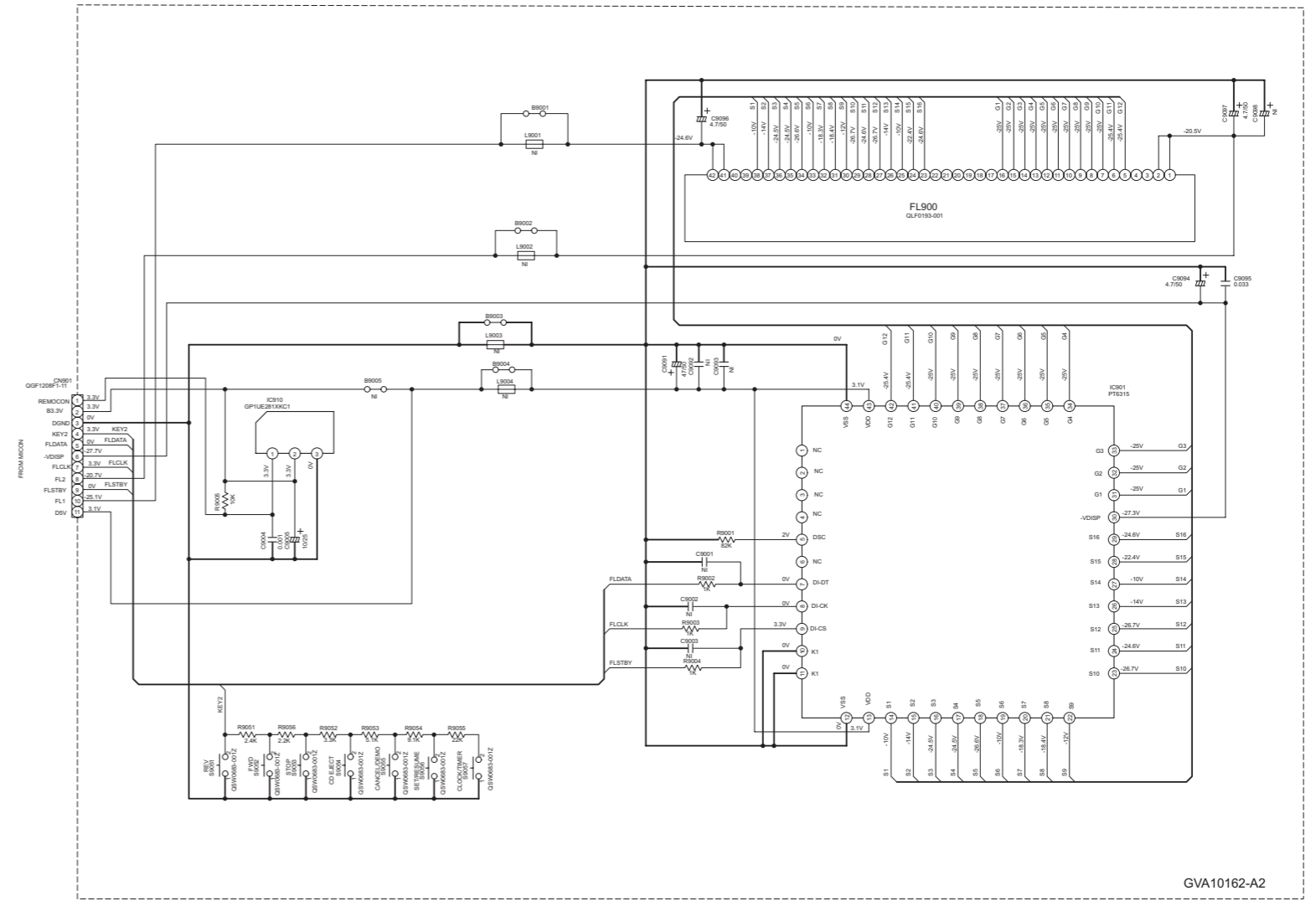
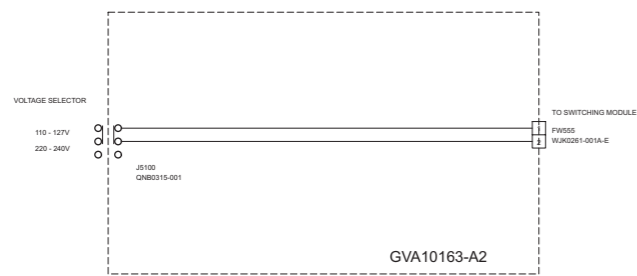
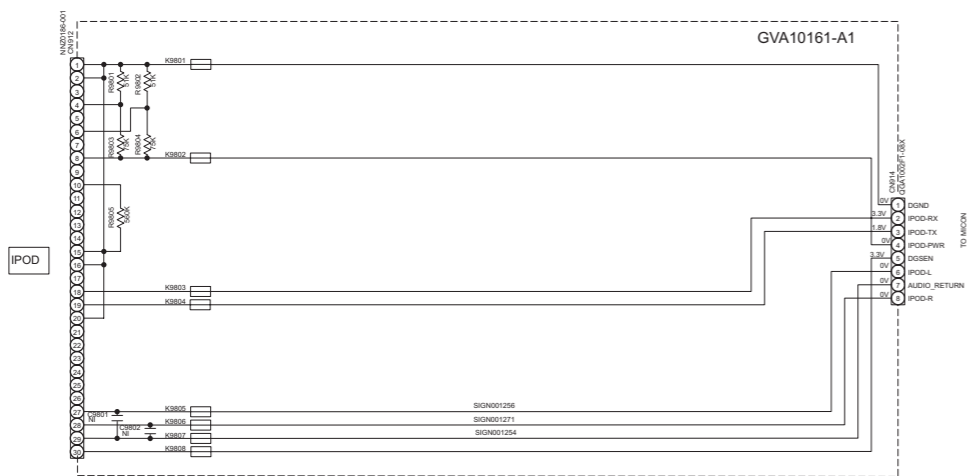
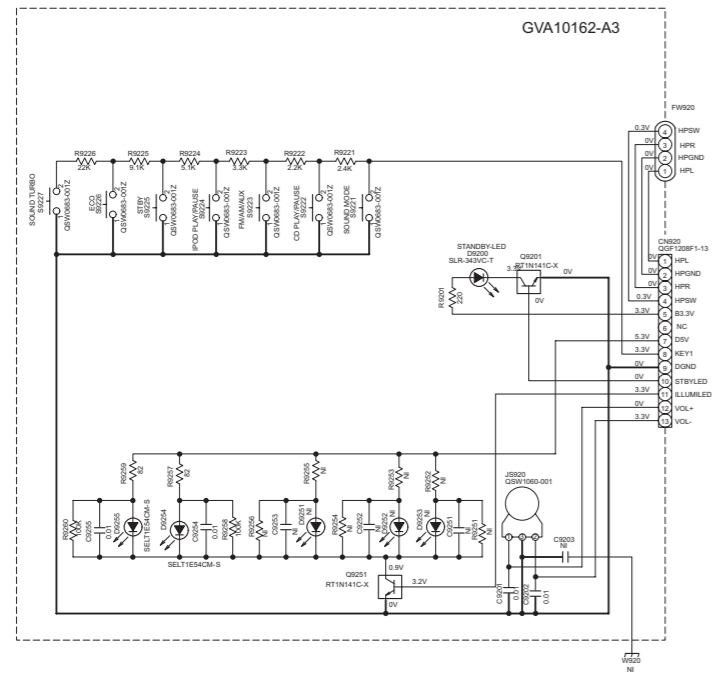
0.2V	9	LEVEL_DET
0V	8	AMP_OSC
2.7V	7	AMP_CTRL
0V	6	AHB_FEEDBACK
0V	5	SW_IN
0V	4	SW_GND
0V	3	R_IN
0V	2	AGND
0V	1	L_IN

FOR MX-KC68 ONLY

\*

MODEL	MX-KC68	MX-KC38
R3601	4.3K	3.9K
R3701	4.3K	3.9K
R3813	4.3K	6.8K

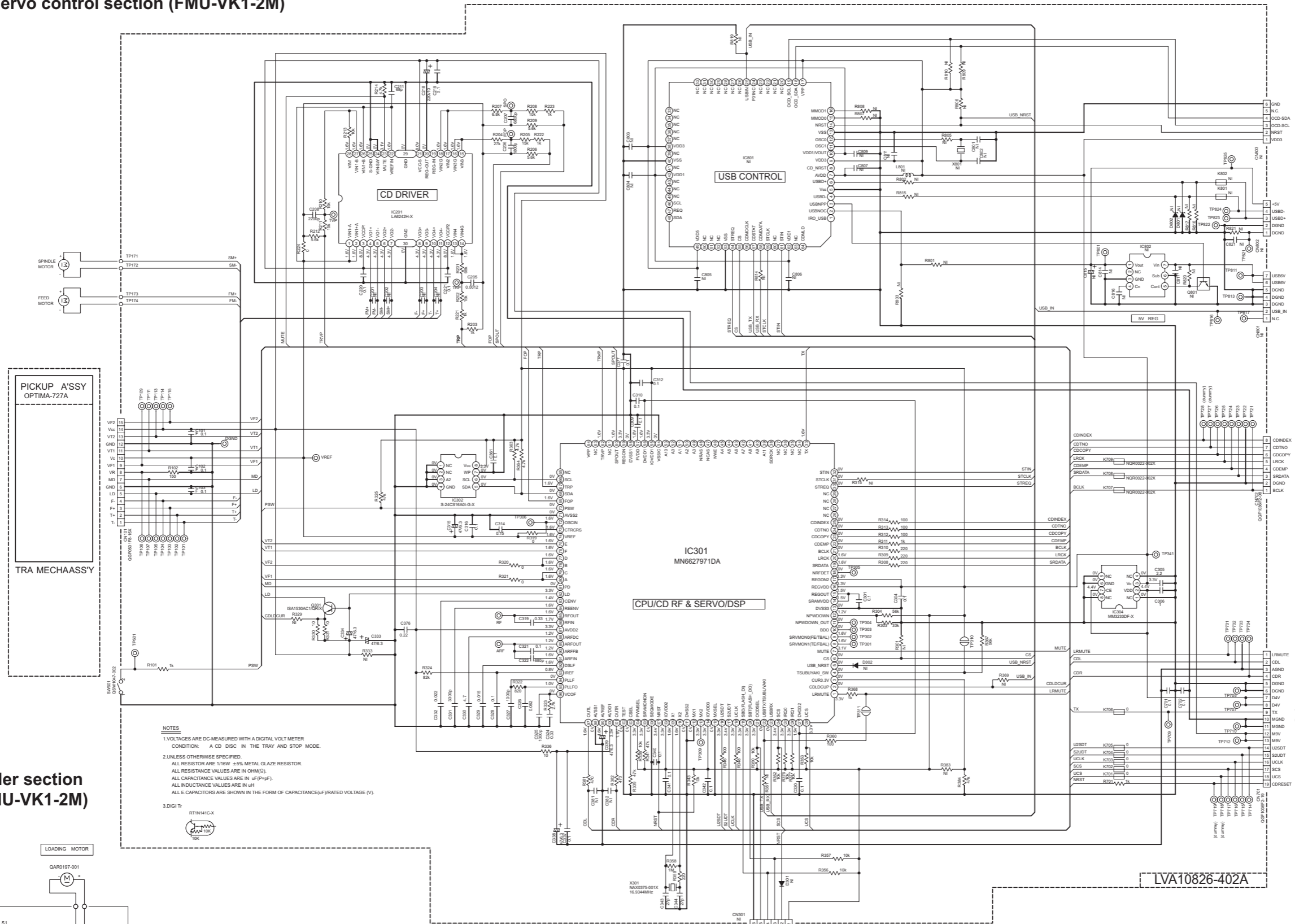
■ Front section





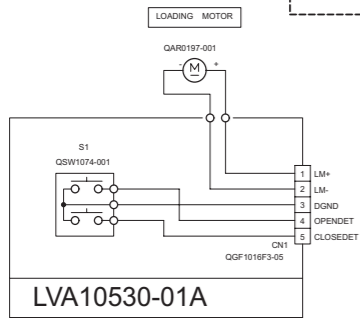


■ CD servo control section (FMU-VK1-2M)



- NOTES
- 1.VOLTAGES ARE DC-MEASURED WITH A DIGITAL VOLT METER CONDITION: A CD DISC IN THE TRAY AND STOP MODE.
  - 2.UNLESS OTHERWISE SPECIFIED, ALL RESISTOR ARE 1/8W ±5% METAL GLAZE RESISTOR. ALL RESISTANCE VALUES ARE IN OHM(Ω). ALL CAPACITANCE VALUES ARE IN μF(μF). ALL INDUCTANCE VALUES ARE IN μH. ALL CAPACITORS ARE SHOWN IN THE FORM OF CAPACITANCE(μF)/RATED VOLTAGE (V).
  - 3.DIGIT: RT1N141C-X

■ Loader section (FMU-VK1-2M)



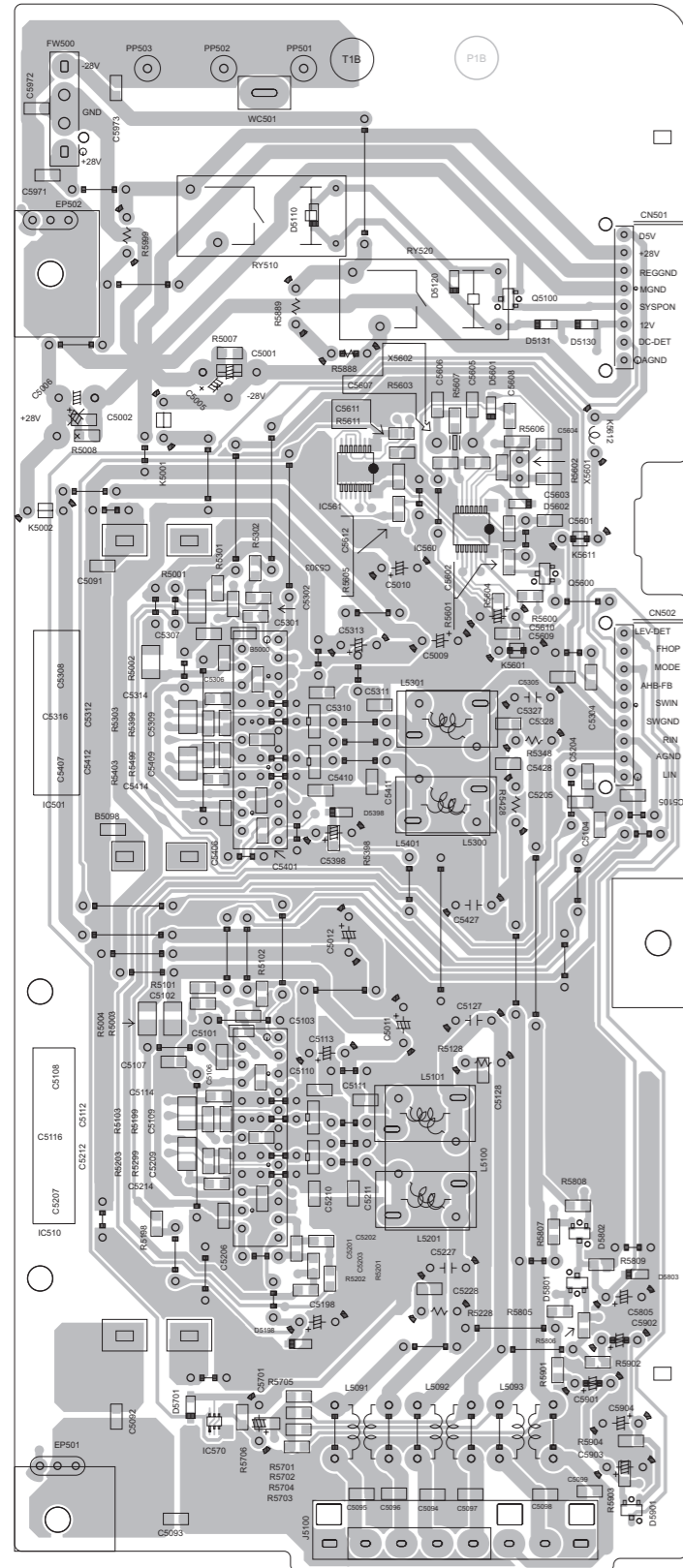
To Micom section 1 CN708

LVA10826-402A

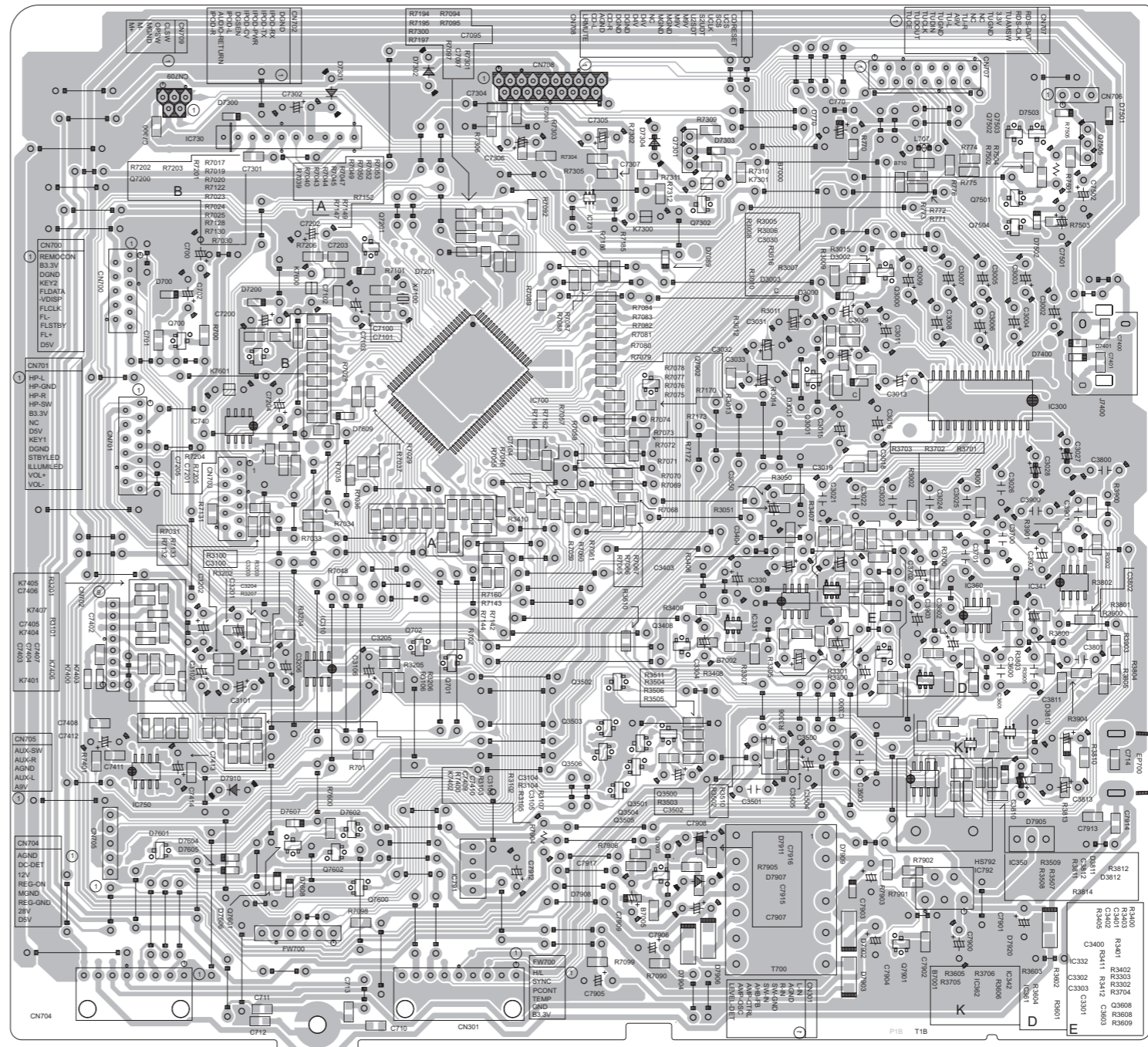
FOR MN6627971 FLASH WRITER

# Printed circuit boards

■ **Power board** Lead free solder used in the board (material : Sn-Ag-Cu, melting point : 219 Centigrade)  
 Lead free solder used in the board (material : Sn-Cu, melting point : 230 Centigrade)



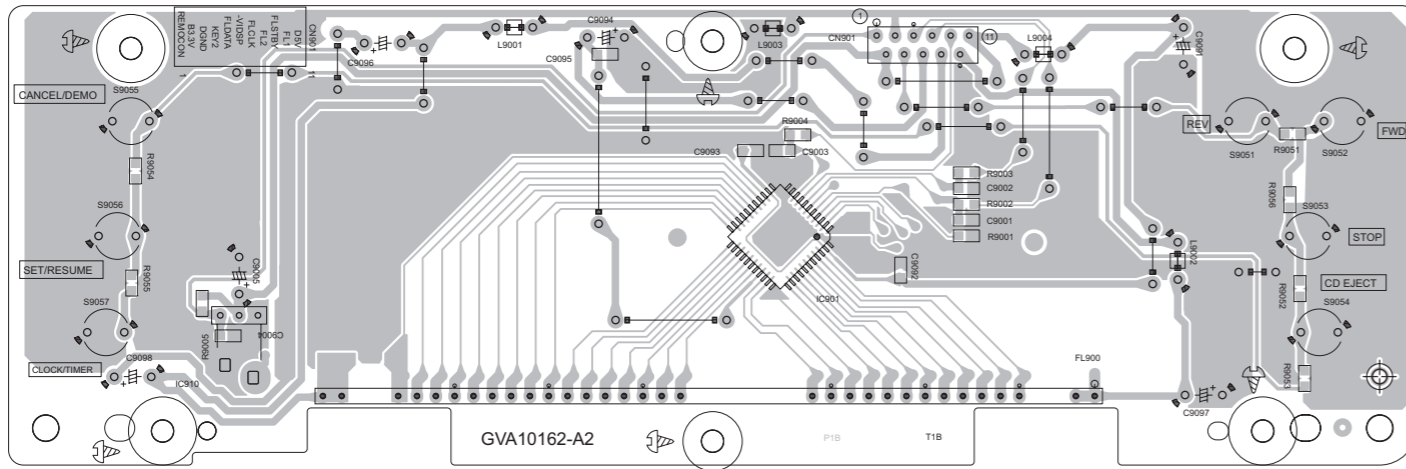
■ **Micom board** Lead free solder used in the board (material : Sn-Ag-Cu, melting point : 219 Centigrade)  
 Lead free solder used in the board (material : Sn-Cu, melting point : 230 Centigrade)



■ **FL board**

Lead free solder used in the board (material : Sn-Ag-Cu, melting point : 219 Centigrade)

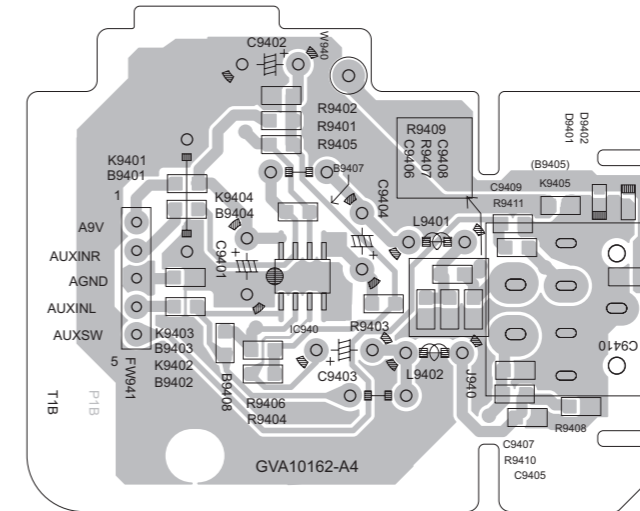
Lead free solder used in the board (material : Sn-Cu, melting point : 230 Centigrade)



■ **AUX jack board**

Lead free solder used in the board (material : Sn-Ag-Cu, melting point : 219 Centigrade)

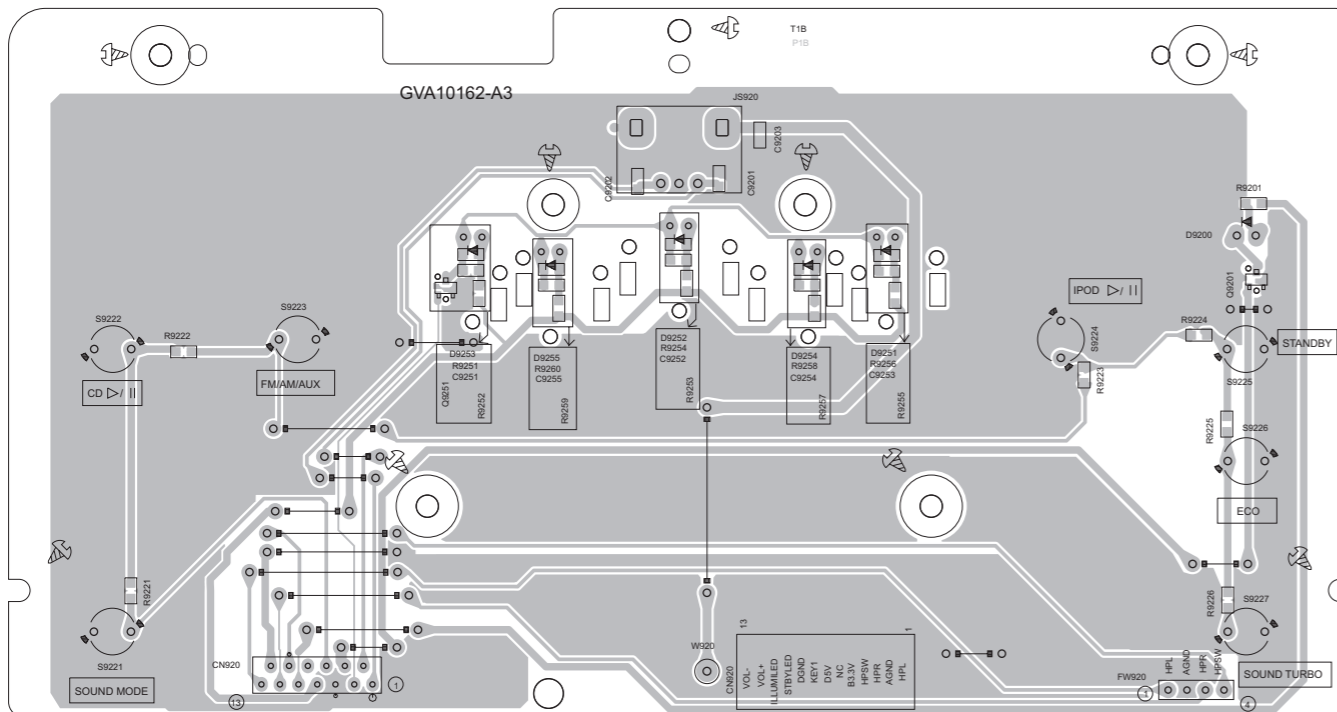
Lead free solder used in the board (material : Sn-Cu, melting point : 230 Centigrade)



■ **Volume board**

Lead free solder used in the board (material : Sn-Ag-Cu, melting point : 219 Centigrade)

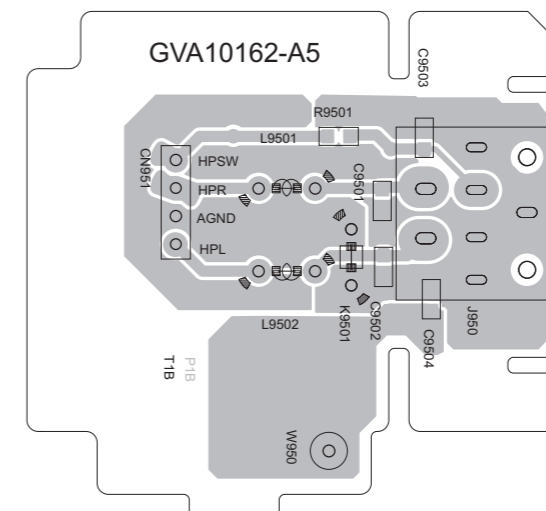
Lead free solder used in the board (material : Sn-Cu, melting point : 230 Centigrade)



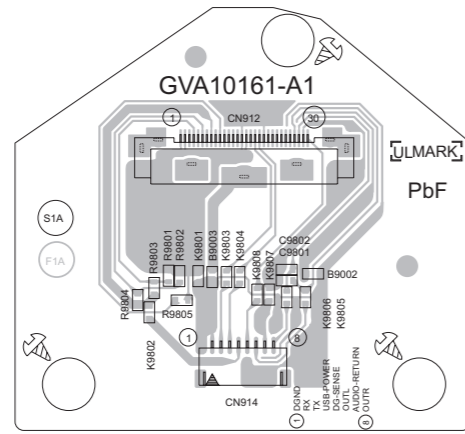
■ **Headphone jack board**

Lead free solder used in the board (material : Sn-Ag-Cu, melting point : 219 Centigrade)

Lead free solder used in the board (material : Sn-Cu, melting point : 230 Centigrade)



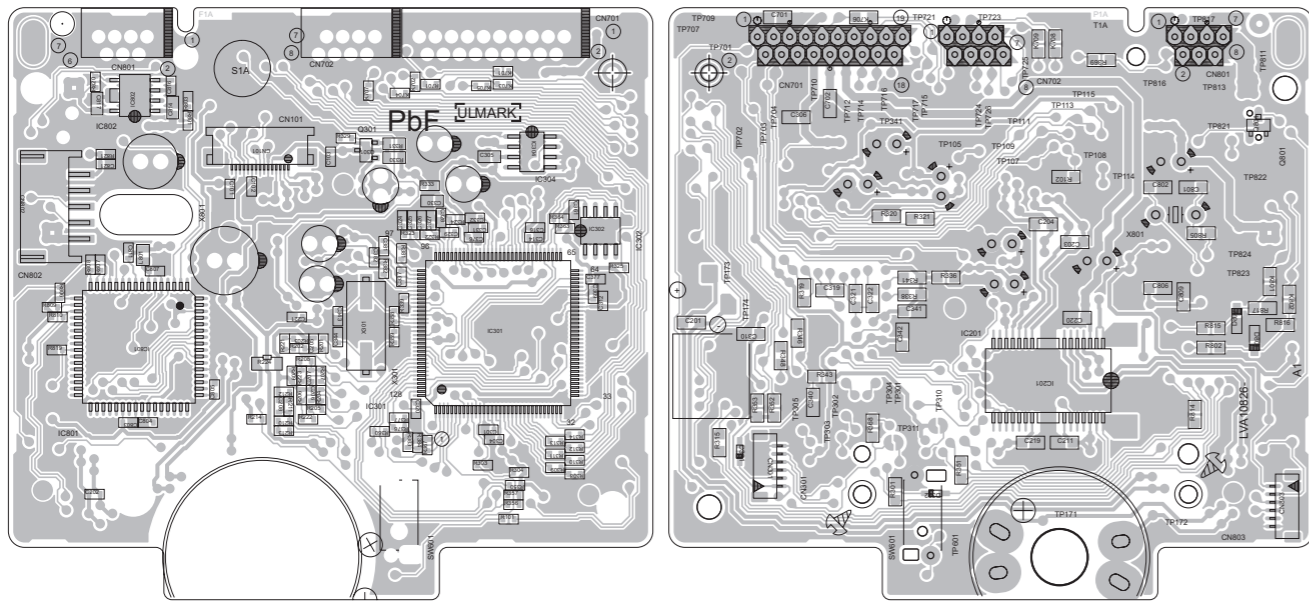
■ iPod board  
 Lead free solder used in the board (material : Sn-Ag-Cu, melting point : 219 Centigrade)  
 Lead free solder used in the board (material : Sn-Cu, melting point : 230 Centigrade)



■ CD servo control board  
 Lead free solder used in the board (material : Sn-Ag-Cu, melting point : 219 Centigrade)  
 Lead free solder used in the board (material : Sn-Cu, melting point : 230 Centigrade)

forward side

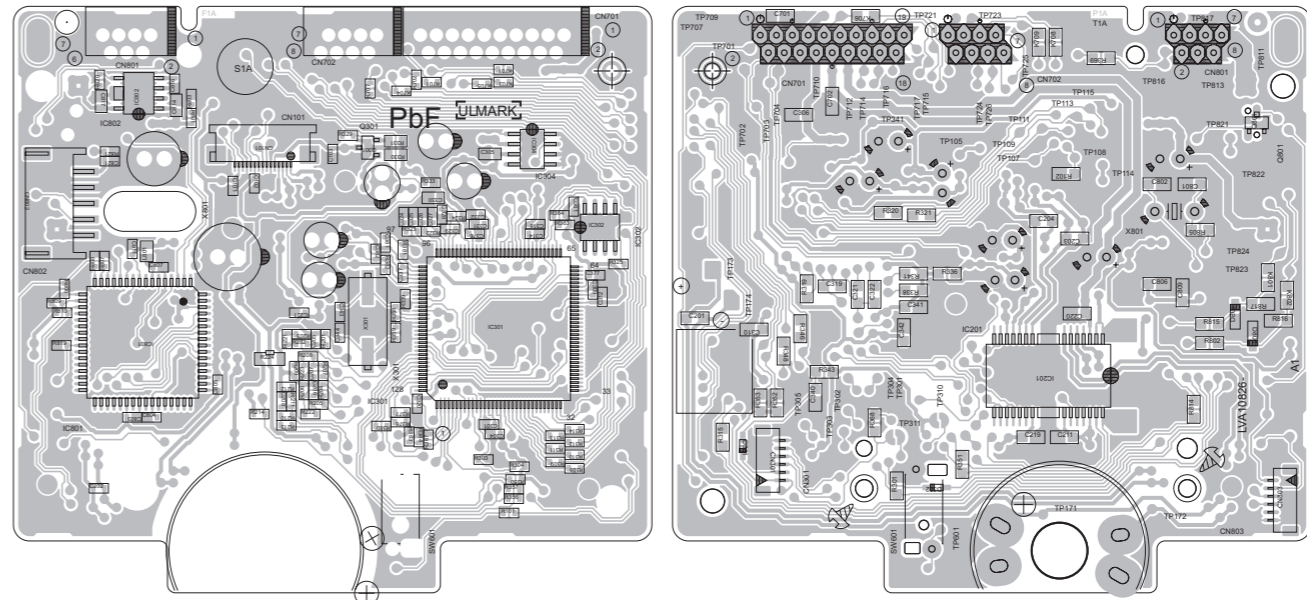
reverse side



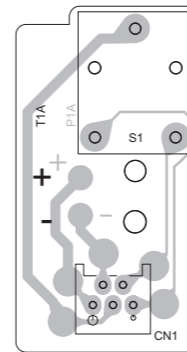
■ CD servo control board (FMU-VK1-2M)  
 Lead free solder used in the board (material : Sn-Ag-Cu, melting point : 219 Centigrade)  
 Lead free solder used in the board (material : Sn-Cu, melting point : 230 Centigrade)

forward side

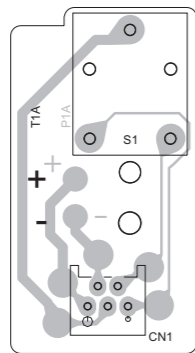
reverse side



■ Loader board (FMU-VK1-2M)  
 Lead free solder used in the board (material : Sn-Ag-Cu, melting point : 219 Centigrade)  
 Lead free solder used in the board (material : Sn-Cu, melting point : 230 Centigrade)



■ Loader board  
 Lead free solder used in the board (material : Sn-Ag-Cu, melting point : 219 Centigrade)  
 Lead free solder used in the board (material : Sn-Cu, melting point : 230 Centigrade)



< MEMO >



Victor Company of Japan, Limited

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